

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJA10P06MX
Package Type :	SOT-89-3L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.78%
Lead Frame	Copper	7440-50-8	97.00%	51.66%
	Iron	7439-89-6	0.08%	
	Phosphorus	7723-14-0	0.02%	
	Silver	7440-22-4	2.90%	
Epoxy	Lead	7439-92-1	80.00%	0.01%
	Tin	7440-31-5	4.00%	
	Silver	7440-22-4	2.00%	
	MIXTURE of(±)-1,3-BUTANEDIOL	107-88-0	13.88%	
	MODIFIED CASTER OIL	61788-85-0	0.12%	
Wire	Copper	7440-50-8	99.99%	0.11%
	Others	/	0.01%	
Mold Compound	Silica	60676-86-0	88.65%	47.15%
	Epoxy Resin	85954-11-6	5.50%	
	Phenol Resin	26834-02-6	5.50%	
	Carbon black	1333-86-4	0.35%	
Plating	Tin	7440-31-5	99.99%	0.29%
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.